

SiI9233A HDMI Receiver with Repeater, Multi-channel Audio, and Deep Color

Data Brief

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Introduction

The SiI9233A HDMI Receiver with Repeater, Multichannel Audio, and Deep Color is a 4-port HDMI® receiver. AV receivers that connect to DTVs displaying 10/12-bit color depth can now provide the highest quality protected digital audio and video, including common 3D formats up to 12-bit, 1080p at 24 Hz resolution. The receiver supports Deep Color video up to 12-bit, 1080p at 60 Hz. Efficient color space conversion receives RGB or YCbCr video data and sends either standard-definition or high-definition RGB or YCbCr formats.

The SiI9233A receiver supports the extended gamut YCC or xvYCC color space, described in the IEC 61966-2-4 specification, that supports approximately 1.8 times the number of colors as the RGB color space. The xvYCC color space also makes full use of the range on the standard 8-bit resolution per pixel.

The SiI9233A receiver is pre-programmed with Highbandwidth Digital Content Protection (HDCP) keys; this helps reduce programming overhead and lowers manufacturing costs.

An integrated Extended Display Identification Data (EDID) block stored in non-volatile memory (NVM) can be programmed at the time of manufacture using the local I²C bus. On-board RAM can also be loaded with EDID data from the system microcontroller during initialization if the NVM is not used. The EDID is reflected on the four HDMI ports through the DDC bus. Flexibility allows mixing different EDID formats in an application. This feature can eliminate up to four EDID ROMs while also saving board space.

Flexible power management provides extremely low standby power consumption; standby power can be supplied from an HDMI 5 V signal or from a separate standby power pin. If the NVM stores the EDID, only the 5 V power from the source device is needed to read the EDID.

Inputs

- Four HDMI/DVI-compatible ports
- TMDS[™] core runs at 25–225 MHz

Digital Video Output

- xvYCC to extended RGB
- 36-bit RGB/YCbCr 4:4:4
- 16/20/24-bit YCbCr 4:2:2
- 8/10/12-bit YCbCr 4:2:2 (ITU BT.656)
- True 12-bit accurate output data using an internal 14-bit wide processing path
- Programmable drive strength from 2 mA to 14 mA

Digital Audio Interface

- DTS-HD and Dolby TrueHD high bit rate audio
- I²S output with 4 data signals for multi-channel formats and flexible, programmable channel mapping
- S/PDIF output supports PCM, Dolby Digital, DTS digital audio transmission with a 32–192 kHz Fs sample rate
- Intelligent audio mute capability avoids pops and noise with automatic soft mute and unmute
- IEC60958 or IEC61937 compatible

Control

- Consumer Electronics Control (CEC) interface incorporates an HDMI CEC I/O and an integrated CEC Programming Interface (CPI)
- Automatic Feature Abort response for unsupported commands and automatic message retry on transmit

Package

20 mm x 20 mm 144-pin TQFP package with ePad[™]

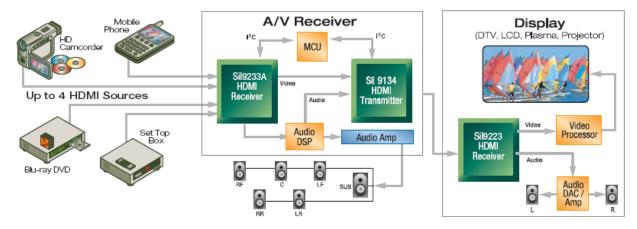


Figure 1. Typical Application

System Applications

The SiI9233A receiver is designed for digital televisions that require support for HDMI Deep Color. The device allows receipt of 10/12-bit color depth up to 1080p resolutions. A single receiver provides four HDMI input ports. The video output interfaces to a video processor and the audio output can interface directly to an audio DAC or an audio DSP for further processing as shown in Figure 1.

Comparing the SiI9233A Receiver with SiI9127A, SiI9223A, SiI9125, and SiI9135A Receivers

Table 1 summarizes the functional differences among the SiI9127A, SiI9125, SiI9135A, SiI9223A, and SiI9233A receivers.

Table 1. Comparison Among Silicon Image Receivers

Table 1. Comparison Among						
Feature	SiI9125	SiI9127A	SiI9135A	SiI9223A	SiI9233A	
HDMI Input Connections						
TMDS Input Ports	2	2	2	4	4	
Color Depth	8/10/12-bit	8/10/12-bit	8/10/12-bit	8/10/12-bit	8/10/12-bit	
DDC Input Ports	2	2	2	4	4	
Maximum TMDS Input Clock	225 MHz	225 MHz	225 MHz	225 MHz	225 MHz	
Video Output						
Digital Video Output Ports	1	1	1	1	1	
Maximum Output Pixel Clock	165 MHz.	165 MHz.	165 MHz.	165 MHz.	165 MHz.	
Maximum Output Bus Width	36	36	36	36	36	
Audio Formats						
S/PDIF Output Ports	1	1	1	1	1	
I ² S Output	2 channel	2 channel	8 channel	2 channel	8 channel	
DSD Output	2 channel	NA	6 channel	NA	8 channel	
High Bit Rate Audio Support Compressed DTS-HD and Dolby True-HD	No	No	Yes	No	Yes	
Maximum Audio Sample Rate (Fs)	192 kHz	192 kHz	192 kHz	192 kHz	192 kHz	
Video Processing						
Color Space Converter	RGB to/from YCbCr	RGB to/from YCbCr xvYCC to RGB	RGB to/from YCbCr	RGB to/from YCbCr xvYCC to RGB	RGB to/from YCbCr xvYCC to RGB	
Pixel Clock Divider	÷ 4, ÷ 2	$\div 4, \div 2$	\div 4, \div 2	÷ 4, ÷ 2	÷ 4, ÷ 2	
Digital Video Bus Mapping	swap Cb, Cr pins	swap Cb, Cr pins	swap Cb, Cr pins	swap Cb, Cr pins	swap Cb, Cr pins	
Other Features						
3D Support	No	No	No	Yes	Yes	
CEC	No	Yes	No	Yes	Yes	
EDID	No	NVRAM	No	NVRAM	NVRAM	
HDCP Repeater Support	No	No	Yes	No	Yes	
Interlaced Format Detection Pin	Yes	Yes	Yes	Yes	Yes	
Package	144-pin TQFP ePad	128-pin TQFP ePad	144-pin TQFP ePad	144-pin TQFP ePad	144-pin TQFP ePad	

Pin Diagram

Figure 2 shows the pin assignments of the SiI9233A receiver. Pin names are generalized by type for this document. The list below the diagram describes the purpose of each type. The package is $20 \text{ mm} \times 20 \text{ mm} \times 144$ -pin TQFP package with $ePad^{TM}$.

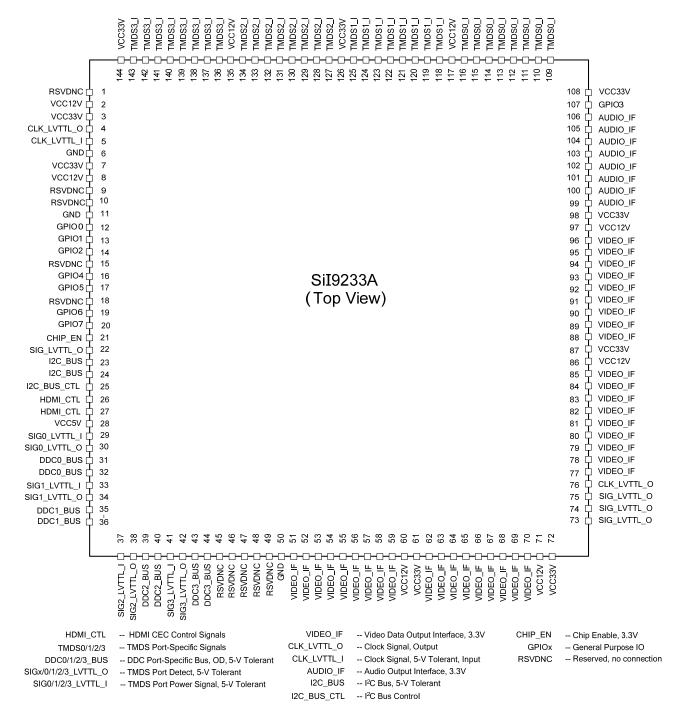


Figure 2. Pin Diagram

Package Information

ePad Requirements

The SiI9233A receiver is packaged in a 144-pin, 20 mm x 20 mm TQFP package with an ExposedPadTM (ePadTM) that is used for the electrical ground of the device and for improved thermal transfer characteristics. The ePad dimensions are 4.445 mm x 4.0604 mm ±0.15 mm. Soldering the ePad to the ground plane of the PCB is *required* to meet package power dissipation requirements at full speed operation, and to correctly connect the chip circuitry to electrical ground. A clearance of at least 0.25 mm should be designed on the PCB between the edge of the ePad and the inner edges of the lead pads to avoid the possibility of electrical shorts.

The thermal land area on the PCB may use thermal vias to improve heat removal from the package. These thermal vias also double as the ground connections of the chip and must attach internally in the PCB to the ground plane. An array of vias should be designed into the PCB beneath the package. For optimum thermal performance, the via diameter should be 12 mils to 13 mils (0.30 mm to 0.33 mm) and the via barrel should be plated with 1-ounce copper to plug the via. This design helps to avoid any solder wicking inside the via during the soldering process, which may result in voids in solder between the pad and the thermal land. If the copper plating does not plug the vias, the thermal vias can be tented with solder mask on the top surface of the PCB to avoid solder wicking inside the via during assembly. The solder mask diameter should be at least 4 mils (0.1 mm) larger than the via diameter.

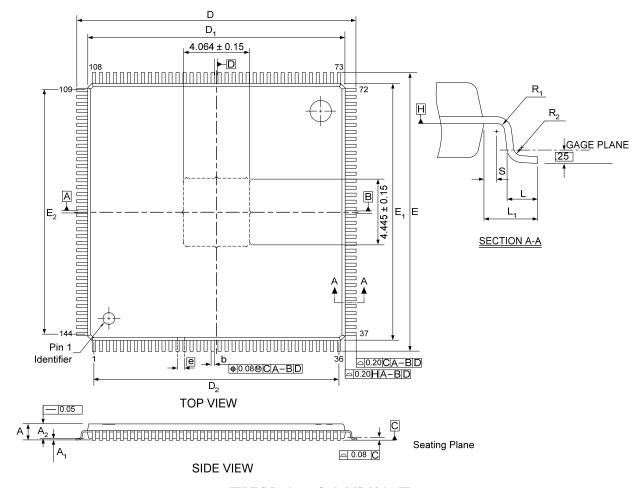
Package stand-off when mounting the device also needs to be considered. For a nominal stand-off of approximately 0.1 mm the stencil thickness of 5 mils to 8 mils should provide a good solder joint between the ePad and the thermal land. Figure 3 on the next page shows the package dimensions of the SiI9233A receiver.

CB Layout Guidelines

Refer to Silicon Image document *PCB Layout Guidelines: Designing with Exposed Pads* for basic PCB design guidelines when designing with thermally enhanced packages using the exposed pad. This application note is intended for use by PCB layout designers.

Package Dimensions

These drawings are not to scale.



JEDEC Package Code MS-026-AFB

Item	Description	Min	Тур	Max
A	Thickness	1.00	1.10	1.20
A1	Stand-off	0.05	0.10	0.15
A2	Body thickness	0.95	1.00	1.05
D	Footprint	22.00 BSC		
Е	Footprint	22.00 BSC		
D_1	Body size	20.00 BSC		
E_1	Body size	20.00 BSC		
D_2	Lead Row Width 17.5 BSC			
E_2	Lead Row Width	17.5 BSC		

Item	Description	Min	Тур	Max
b	Lead width	0.17	0.22	0.27
С	Lead thickness	0.09		0.20
e	Lead pitch	0.50 BSC		
L	Lead foot length	0.45	0.60	0.75
L_1	Total lead length	1.00 REF		
R_1	Lead radius, inside	0.08		
R_2	Lead radius, outside	0.08		0.20
S	Lead horizontal run	0.20	_	_

Dimensions in millimeters.

Overall thickness A = A1 + A2.

Figure 3. 144-Pin TQFP Package Diagram

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Marking Specification

Figure 4 shows the markings of the SiI9233A package. Refer to specifics in Figure 3 on page 5.

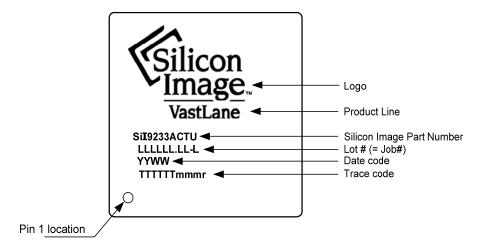


Figure 4. Marking Diagram

Ordering Information

Production Part Numbers:

TMDS Input Clock Range	Part Number	
25–225 MHz	SiI9233ACTU	

The universal package may be used in lead-free and ordinary process lines.

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